5 é

TVS

0->VBR 1ps

3000W

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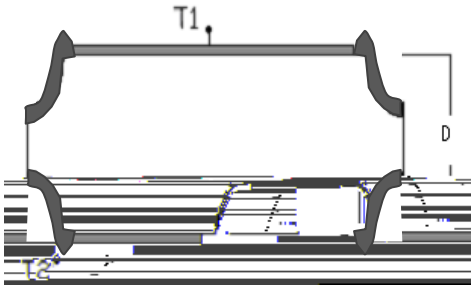
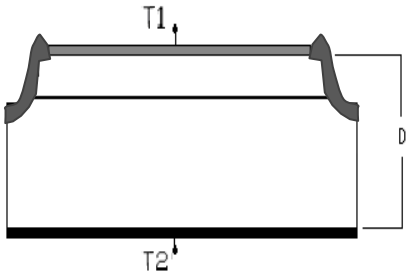
Wafer tech		
Wafer Size	5inch	
Chip Thickness	D=265 15 m( )	
T1/T2 Metal	Front	TiNiAg
	Back	TiNiAg
Chip Size	(A: m) Chip	ð ì ò ð F ñ ì
	(B: m) Pad	ï ñ ñ ò î ñ s Z õ s ï ó ò õ î ñ s Z õ s



1 TVS



2 TVS



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